MMBD2837LT1G, MMBD2838LT1G, SMMBD2837LT1G

Monolithic Dual Switching Diodes

Features

- AEC-Q101 Qualified and PPAP Capable
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant*

MAXIMUM RATINGS (EACH DIODE)

Rating	Symbol	Value	Unit
Peak Reverse Voltage	V _{RM}	75	Vdc
D.C. Reverse Voltage MMBD2837LT1G, SMMBD2837LT1G MMBD2838LT1G	V _R	30 50	Vdc
Peak Forward Current	I _{FM}	450 300	mAdc
Average Rectified Current	Ι _Ο	150 100	mAdc

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Total Device Dissipation FR-5 Board (Note 1) $T_A = 25^{\circ}C$ Derate above 25°C	P _D	225 1.8	mW mW/°C
Defate above 25 C		1.0	IIIVV/ C
Thermal Resistance,	$R_{\theta JA}$		°C/W
Junction-to-Ambient		556	
Total Device Dissipation Alumina Substrate, (Note 2) $T_A = 25^{\circ}C$	PD	300	mW
Derate above 25°C		2.4	mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T _J , T _{stg}	–55 to +150	°C

1. FR-5 = $1.0 \times 0.75 \times 0.062$ in.

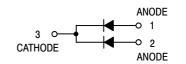
2. Alumina = 0.4 \times 0.3 \times 0.024 in. 99.5% alumina.



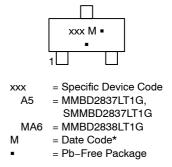
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MARKING DIAGRAM



(Note: Microdot may be in either location) *Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
MMBD2837LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
SMMBD2837LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
MMBD2838LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel

+ For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

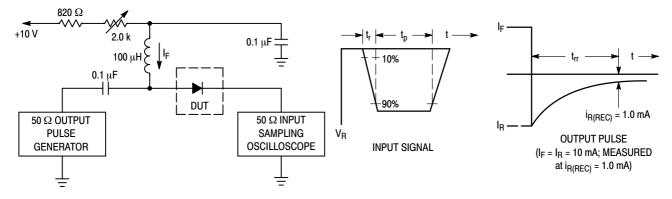
MMBD2837LT1G, MMBD2838LT1G, SMMBD2837LT1G

ELECTRICAL CHARACTERISTICS (EACH DIODE) (T _A = 25°C unless otherwise noted)	ELECTRICAL CHARACTERISTICS	(EACH DIODE)	$(T_A = 25^{\circ}C \text{ unless otherwise noted})$
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Characteristic	Symbol	Min	Max	Unit

OFF CHARACTERISTICS				
Reverse Breakdown Voltage (I _(BR) = 100 μAdc) MMBD2837LT1G, SMMBD2837LT1G MMBD2838LT1G	V _(BR)	35 75		Vdc
Reverse Voltage Leakage Current (Note 3.) ($V_R = 30 Vdc$) MMBD2837LT1G, SMMBD2837LT1G ($V_R = 50 Vdc$) MMBD2838LT1G	I _R	-	0.1 0.1	μAdc
Diode Capacitance (V _R = 0 V, f = 1.0 MHz)	C _T	-	4.0	pF
Forward Voltage $(I_F = 10 \text{ mAdc})$ $(I_F = 50 \text{ mAdc})$ $(I_F = 100 \text{ mAdc})$	V _F	- - -	1.0 1.0 1.2	Vdc
Reverse Recovery Time ($I_F = I_R = 10 \text{ mAdc}, I_{R(REC)} = 1.0 \text{ mAdc}$) (Figure 1)	t _{rr}	-	4.0	ns

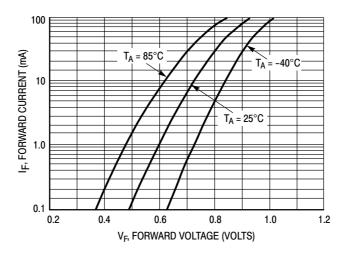
3. For each individual diode while the second diode is unbiased.



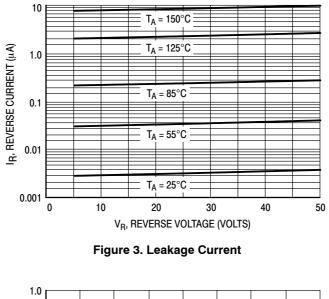
Notes: 1. A 2.0 k Ω variable resistor adjusted for a Forward Current (I_F) of 10 mA. Notes: 2. Input pulse is adjusted so I_{R(peak)} is equal to 10 mA. Notes: 3. t_p » t_{rr}

Figure 1. Recovery Time Equivalent Test Circuit

CURVES APPLICABLE TO EACH CATHODE







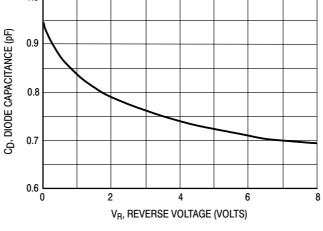
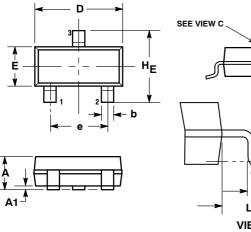


Figure 4. Capacitance

MMBD2837LT1G, MMBD2838LT1G, SMMBD2837LT1G

PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 ISSUE AP



0.25 L L1 VIEW C

NOTES:

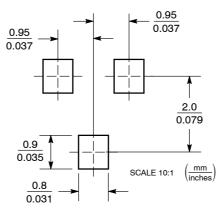
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.
 - MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH
- 3 THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, 4. PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
С	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104
θ	0°		10°	0°		10°

STYLE 9: PIN 1. ANODE

2. ANODE З. CATHODE

SOLDERING FOOTPRINT



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